

L Number	Hits	Search Text	DB	Time stamp
1	465825	(stack stacking stacked stackable multiple level plurality) with (substrate semiconductor die dice ic chip (integrated adj circuit))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/06 16:25
2	352735	heat with (sink cover lid stiffener radiate radiation radiating radiated dissipation dissipating dissipated dissipate slug)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/06 16:26
3	9382	(heat with (sink cover lid stiffener radiate radiation radiating radiated dissipation dissipating dissipated dissipate slug)) same ((stack stacking stacked stackable multiple level plurality) with (substrate semiconductor die dice ic chip (integrated adj circuit)) )	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/06 16:26
4	5412	(heat with (sink cover lid stiffener radiate radiation radiating radiated dissipation dissipating dissipated dissipate slug)) with ((stack stacking stacked stackable multiple level plurality) with (substrate semiconductor die dice ic chip (integrated adj circuit)) )	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/06 16:27
5	1317	(epoxy mold moulded molded encase encased encasing encapsulant encapsulate encapsulating encapsulation encapsulated) same ((heat with (sink cover lid stiffener radiate radiation radiating radiated dissipation dissipating dissipated dissipate slug)) same ((stack stacking stacked stackable multiple level plurality) with (substrate semiconductor die dice ic chip (integrated adj circuit)) ))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/06 16:28
6	380	(epoxy mold moulded molded encase encased encasing encapsulant encapsulate encapsulating encapsulation encapsulated) with ((heat with (sink cover lid stiffener radiate radiation radiating radiated dissipation dissipating dissipated dissipate slug)) with ((stack stacking stacked stackable multiple level plurality) with (substrate semiconductor die dice ic chip (integrated adj circuit)) ))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/06 16:52
7	1		USPAT	2004/09/06 16:34
8	1		USPAT	2004/09/06 16:34
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13	1		USPAT	2004/09/06 16:35
14	1		USPAT	2004/09/06 16:35
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24	1		USPAT	2004/09/06 16:36
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53	1		USPAT	2004/09/06 16:41
54	1		USPAT	2004/09/06 16:41
55	1		USPAT	2004/09/06 16:41
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58	1		USPAT	2004/09/06 16:41
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61	1		USPAT	2004/09/06 16:42
62	1		USPAT	2004/09/06 16:42
63	1		USPAT	2004/09/06 16:42
64	1		USPAT	2004/09/06 16:42
65	1		USPAT	2004/09/06 16:43
66	1		USPAT	2004/09/06 16:43
67	937	((epoxy mold moulded molded encase encased encasing encapsulant encapsulate encapsulating encapsulation encapsulated) same ((heat with (sink cover lid stiffener radiate radiation radiating radiated dissipation dissipating dissipated dissipate slug)) same ((stack stacking stacked stackable multiple level plurality) with (substrate semiconductor die dice ic chip (integrated adj circuit)) ))) not ((epoxy mold moulded molded encase encased encasing encapsulant encapsulate encapsulating encapsulation encapsulated) with ((heat with (sink cover lid stiffener radiate radiation radiating radiated dissipation dissipating dissipated dissipate slug)) with ((stack stacking stacked stackable multiple level plurality) with (substrate semiconductor die dice ic chip (integrated adj circuit)) )))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/06 16:53